

The listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Original) A thin film integrated circuit device comprising:  
an insulating film;  
a plurality of semiconductor films isolated from one another, which are provided over one surface of the insulating film;  
a thin film integrated circuit having the plurality of semiconductor films; and  
a metal oxide provided over the other surface of the insulating film.
2. (Original) A thin film integrated circuit device according to claim 1, wherein the metal oxide comprises  $\text{WO}_2$  or  $\text{WO}_3$ .
3. (Original) A thin film integrated circuit device according to claim 1, wherein the metal oxide is an oxide of an element selected from the group consisting of W, Ti, Ta, Mo, Nd, Ni, Co, Zr, Zn, Ru, Rh, Pd, Os, and Ir; an alloy containing the metal as a main component; or a chemical compound thereof.
4. (Original) A thin film integrated circuit device according to claim 1, wherein each of the plurality of semiconductor films functions as an active region
5. (Original) A thin film integrated circuit device according to claim 1, wherein each of the plurality of semiconductor films functions as a channel region.
6. (Original) An IC label comprising:  
an insulating film;  
a plurality of semiconductor films isolated from one another which are provided over one surface of the insulating film;  
a thin film integrated circuit having the plurality of semiconductor films as an active

region; and

an affixing means for affixing a surface of the IC label to a container.

7. (Original) An IC label according to claim 6, wherein the IC label is a contactless type.

8. (Original) An IC label according to claim 6, wherein the other surface of the IC label can be printed with a character, a letter, text, a symbol, or a diagram.

9. (Original) An IC label comprising a contactless thin film integrated circuit, said IC label being adhered to a container,

wherein the thin film integrated circuit comprises:

a plurality of semiconductor film isolated from one another which are provided over an insulating film as an active region;

a gate electrode provided over the semiconductor film; and

an antenna in a same layer as the gate electrode.

10. (Original) An IC label according to claim 9, wherein the antenna is formed from a same material as the gate electrode.

11. (Original) An IC label according to claim 9, wherein the antenna comprises a conductive paste.

12. (Original) An IC label comprising a contactless thin film integrated circuit, said IC label being adhered to a container,

wherein the thin film integrated circuit comprises:

a plurality of semiconductor film isolated from one another which are provided over an insulating film as an active region;

a wiring connected to an impurity region of the semiconductor film; and

an antenna in a same layer as the wiring.

13. (Original) An IC label according to claim 12, wherein the antenna comprises a same

material as the gate wiring.

14. (Original) An IC label according to claim 12, wherein the antenna comprises a conductive paste.

15. (Original) A container comprising:  
an insulating film;  
a plurality of semiconductor films isolated from one another, which are provided over one surface of the insulating film; and  
a thin film integrated circuit having the plurality of semiconductor films as an active region,  
wherein the thin film integrated circuit is adhered to the container.

16. (Original) A container according to claim 15, wherein the thin film integrated circuit is covered by a label.

17. (Original) A container according to claim 16, wherein a protective film having a DLC film or a CN film is provided between the thin film integrated circuit and the label.

18. (Original) A container according to claim 15, wherein the thin film integrated circuit is held between a first label and a second label, and the second label is affixed to the thin film integrated circuit with an adhesive agent.

19. (Original) A container according to claim 15,  
wherein a metal oxide is provided over the other side of the insulating film; and  
wherein the metal oxide is adhered to the container.

20. (Original) A container comprising a contactless thin film integrated circuit that is adhered to the container,  
wherein the thin film integrated circuit comprises:  
a plurality of semiconductor films isolated from one another which are provided over one

surface of an insulating film as an active region;

a gate electrode that is provided over the plurality of semiconductor films; and  
an antenna that is provided in a same layer as the gate electrode,  
wherein the other surface of the insulating film comprises a metal oxide.

21. (Original) A container according to claim 20, wherein the thin film integrated circuit is covered by a label.

22. (Original) A container according to claim 21, wherein a protective film having a DLC film or a CN film is provided between the thin film integrated circuit and the label.

23. (Original) A container according to claim 20, wherein the thin film integrated circuit is held between a first label and a second label, and the second label is affixed to the thin film integrated circuit with an adhesive agent.

24. (Original) A container comprising a contactless thin film integrated circuit that is adhered to a container,

wherein the thin film integrated circuit comprises:

a plurality of semiconductor films isolated from one another which are provided over one surface of an insulating film as an active region;

a wiring provided over the plurality of semiconductor films; and

an antenna provided in a same layer as the wiring,

wherein the other surface of the insulating film comprises a metal oxide.

25. (Original) A container according to claim 24, wherein the thin film integrated circuit is covered by a label.

26. (Original) A container according to claim 25, wherein a protective film having a DLC film or a CN film is provided between the thin film integrated circuit and the label.

27. (Original) A container according to claim 24, wherein the thin film integrated circuit

is held between a first label and a second label, and the second label is affixed to the thin film integrated circuit with an adhesive agent.

28.-60. (Canceled)